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WHAT IS CLAIMED IS:

1. A semiconductor laser package comprising:

an island member formed of metal, including a base plane and a block member protruding in a direction substantially perpendicular to said base plane,

a lead,

a resin member molded integrally with said island member and said lead so as to fix a relative position relationship between said island member and said lead,

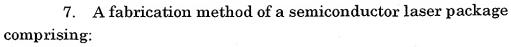
a laser chip fixed at said block member so as to enable emission of a laser beam in a direction substantially perpendicular to said base plane, and a light receiving unit directly fixed at said resin member.

- 2. The semiconductor laser package according to claim 1, wherein said resin member has a light receiving unit attaching plane substantially parallel to said base plane, and said light receiving unit is mounted at said light receiving unit attaching plane.
- 3. The semiconductor laser package according to claim 1, wherein a heat radiator is fixed at said block unit, and said laser chip is fixed to said block unit so as to form contact with said heat radiator.
- 4. The semiconductor laser package according to claim 3, wherein said heat radiator comprises light receiving means.
- 5. The semiconductor laser package according to claim 1, wherein a hologram element is arranged located on an optical path of a laser beam emitted from said laser chip.
- 6. The semiconductor laser package according to claim 1, comprising a cover to enclose said laser chip and said light receiving unit.

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a resin member molding step of molding an island member formed of metal, including a base plane and a block member protruding substantially in a direction of a normal line to said base plane, and a lead integrally with resin so as to fix a relative position relationship between said island member and lead,

a laser chip attaching step of fixing a laser chip at said block member so as to enable emission of a laser beam in a direction of the normal line of said base plane, and

a light receiving unit attaching step of fixing a light receiving unit at said resin member.

- 8. The fabrication method of a semiconductor laser package according to claim 7, wherein said resin member molding step includes the step of arranging said island member and said lead in a same resin molding die and effect resin molding.
- 9. The fabrication method of a semiconductor laser package according to claim 7, further comprising an island member formation step of forming said island member by cold forging.
- 10. The fabrication method of a semiconductor laser package according to claim 7, wherein said lead is formed by shaping through pressworking, and applying a bending process.
- 11. An optical pick up apparatus comprising a semiconductor laser package defined in claim 1, and a lens, wherein said lens is fixed so that a focal point substantially matches a light emitting point of said laser chip.